

METHOD AND APPARATUS FOR PEELING SURFACE PROTECTIVE FILM

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ABSTRACT OF THE DISCLOSURE

10 A method and an apparatus for peeling a surface
protective film attached on the surface of a
semiconductor wafer are provided. A heating block is set
in proximity to the whole surface of the semiconductor
wafer, and the whole surface protective film is heated by
the heating block. Thus, the air bubbles existing
between the semiconductor wafer and the surface
15 protective film are expanded or swelled, and the adhesion
between the semiconductor wafer and the surface
protective film is weakened. After that, the surface
protective film is peeled from the semiconductor wafer.
As a result, a peel starting point can be appropriately
20 formed and damage to the wafer can be prevented.

Fig. 4